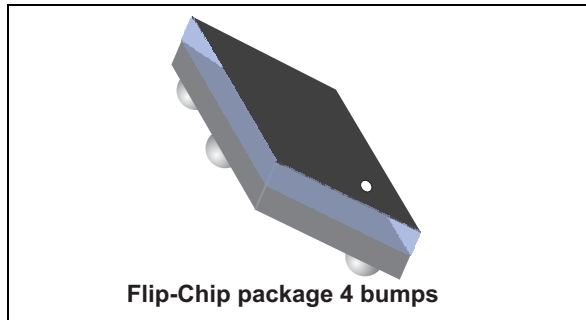


50 ohm nominal input / conjugate match balun for STLC2690, with integrated harmonic filter

Datasheet – production data



Features

- 50 Ω nominal input / matched output differential impedance
- Integrated harmonic filter
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint < 1.54 mm²

Benefits

- Very low profile (< 560 μm after reflow)
- High RF performance
- RF BOM and area reduction

Applications

- Bluetooth STLC2690 application
- Mobile phone application

Description

STMicroelectronics BALF-2690-02D3 is a balun design to transform single ended signal to differential signals in Bluetooth applications. This BALF-2690-02D3 has been customized for STLC2690 Bluetooth transceiver with less than 1.2 dB insertion losses in the bandwidth (2400 MHz-2500 MHz).

The BALF-2690-02D3 has been designed using STMicroelectronics IPD (integrated passive device) technology on non-conductive glass substrate which optimize RF performances.

Figure 1. Device configuration (top view)

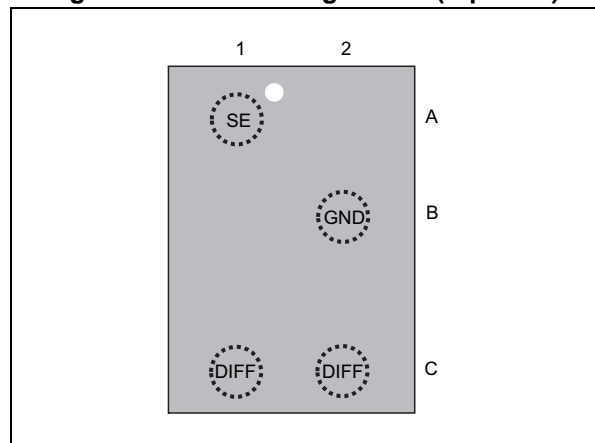
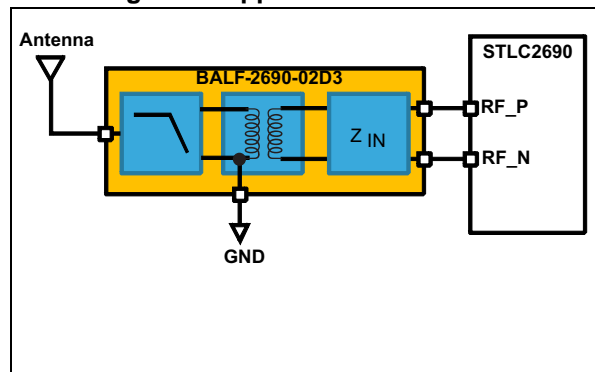


Figure 2. Application schematic



1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
P_{IN}	Input power RFIN		10	13	dBm
V_{ESD}	ESD rating, human body model (JESD22-A114-C) all I/O one at a time while others connected to GND	2000			V
	ESD rating, machine model, all I/O	200			
T_{OP}	Operating temperature range	-40		+85	°C

Table 2. Impedances ($T_{amb} = 25\text{ °C}$)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
Z_{DIFF}	Nominal differential impedance		matched to STLC2690		Ω
Z_{SE}	Nominal single-ended impedance		50		

Table 3. RF performance ($T_{amb} = 25\text{ °C}$)

Symbol	Parameter	Test condition	Value			Unit
			Min.	Typ.	Max.	
f	Frequency range (bandwidth)		2400		2500	MHz
I_L	Insertion loss in bandwidth			+1.2		dB
R_{L_SE}	Return loss in bandwidth		15	21		dB
Φ_{imb}	Output phase imbalance (single ended)		-10		+10	°
A_{imb}	Output amplitude imbalance		-1	0.5	1	dB
CMRR	Common mode rejection (S_{SC12})		20			dB
Att_{2f_0}	2nd harmonic S21 attenuation	4800-5000 MHz	31			dB
Att_{3f_0}	3rd harmonic S21 attenuation	7200-7500 MHz	36			

1.1 Measurements

Figure 3. Return loss ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

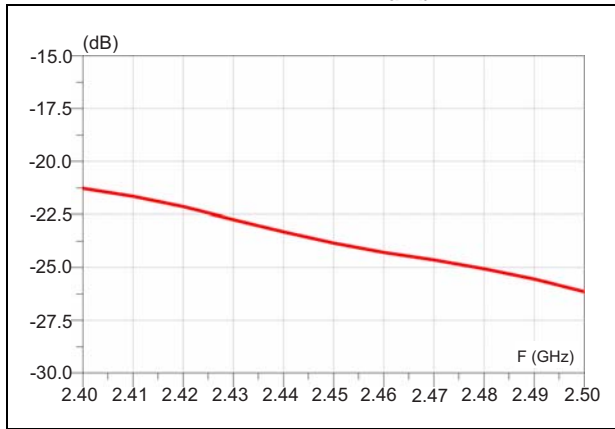


Figure 4. Insertion loss ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

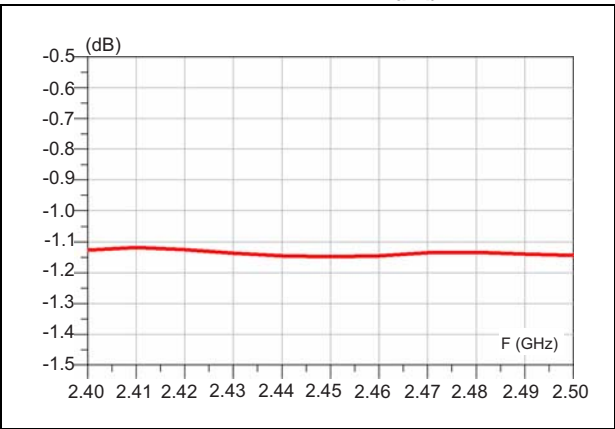


Figure 5. Phase imbalance ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

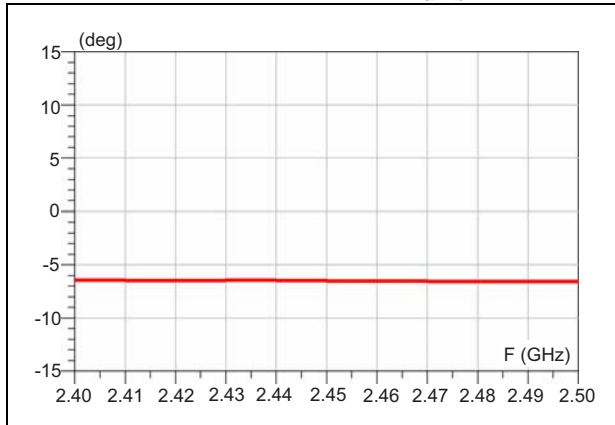


Figure 6. Amplitude imbalance ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

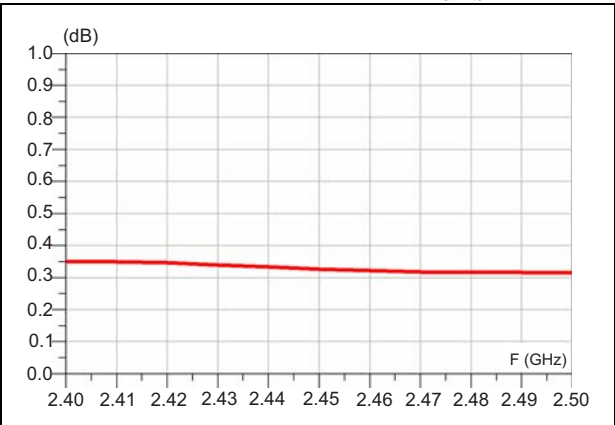


Figure 7. Transmission: 2nd harmonic (dB) ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

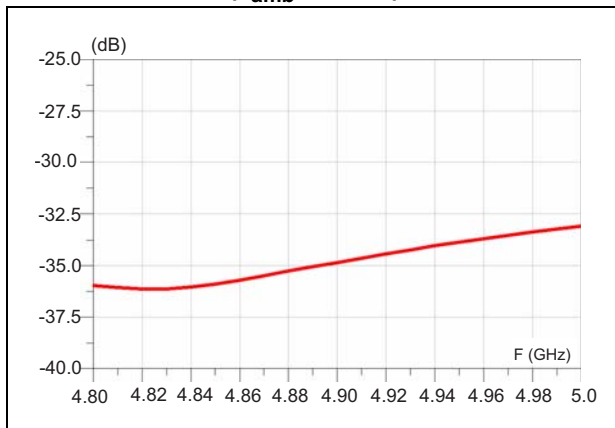


Figure 8. Transmission: 3rd harmonic (dB) ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

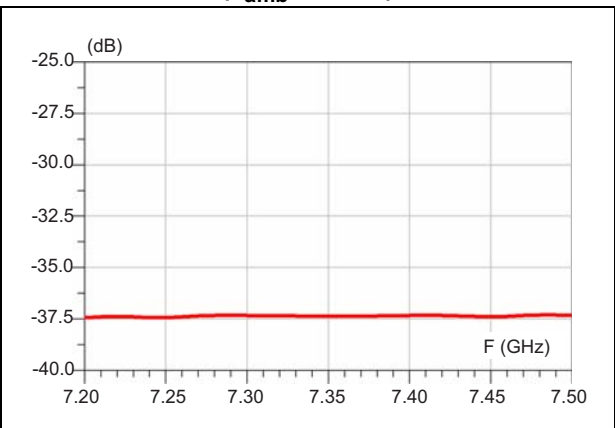
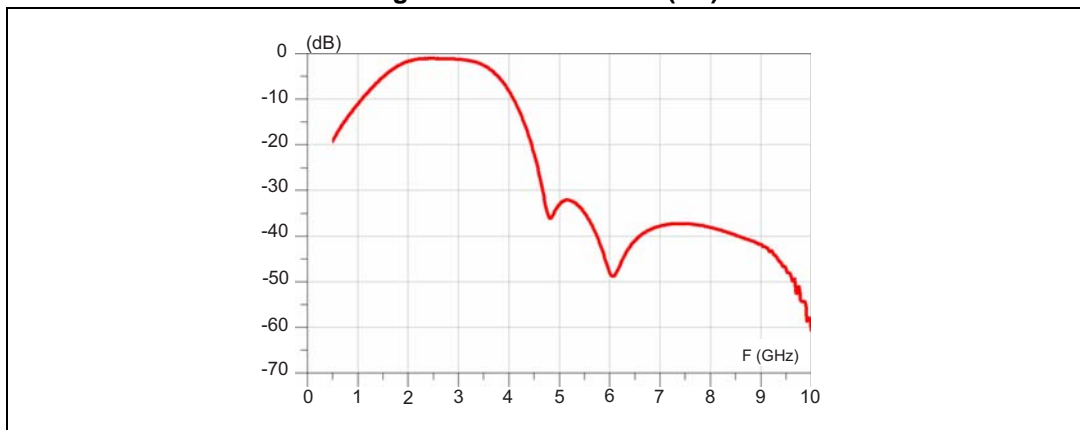


Figure 9. Transmission (dB)



2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 10. Package dimensions

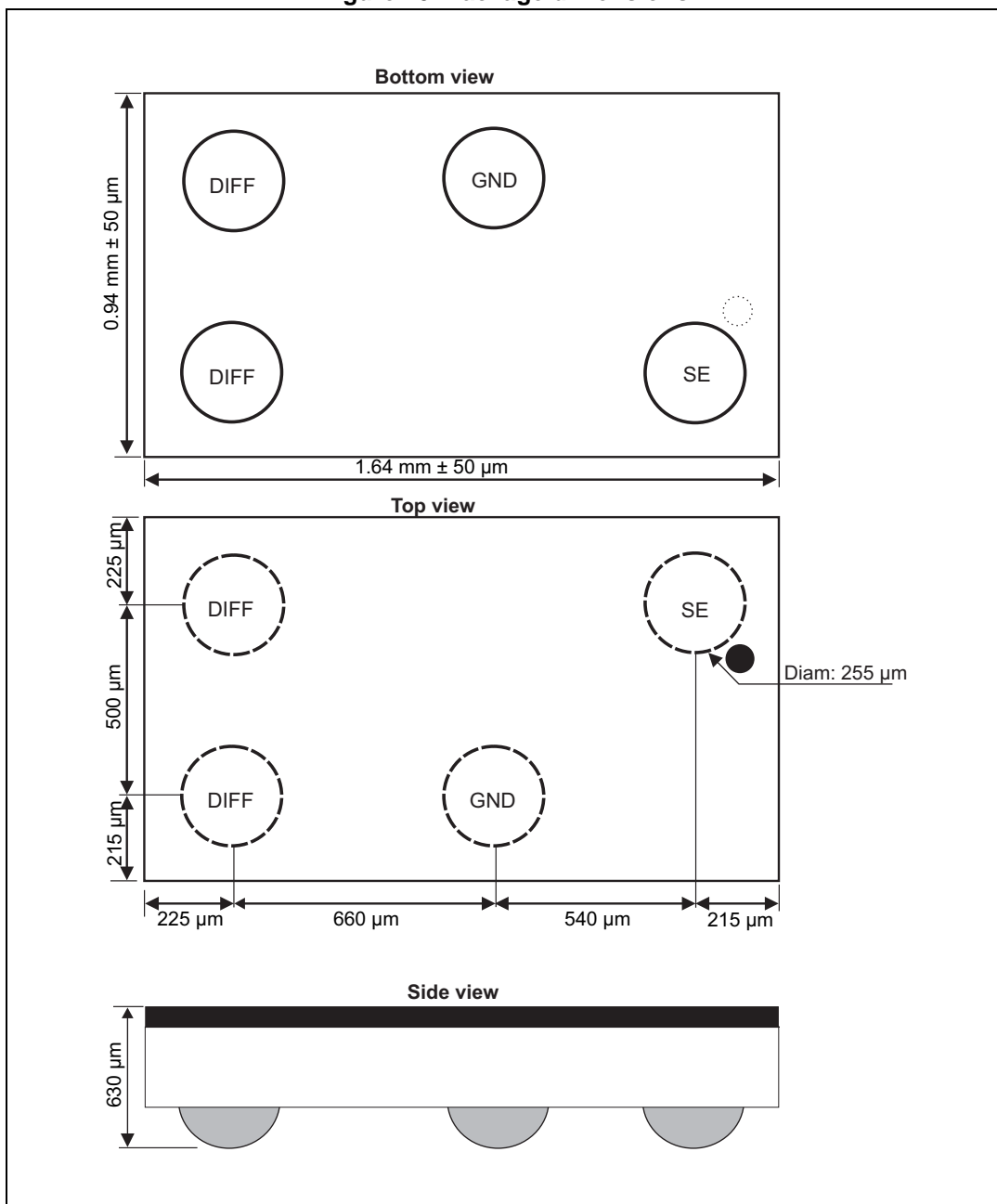


Figure 11. Footprint - non solder mask defined

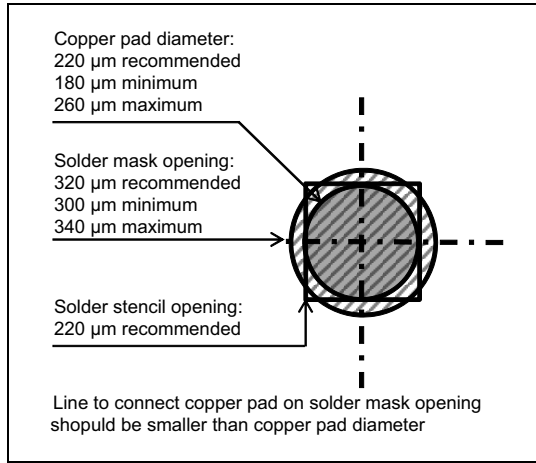


Figure 12. Footprint - solder mask defined

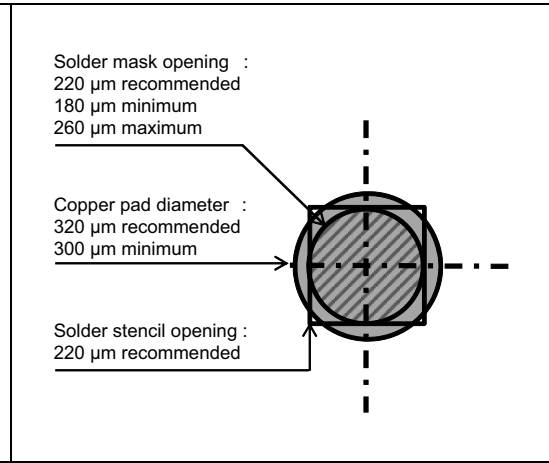


Figure 13. Marking

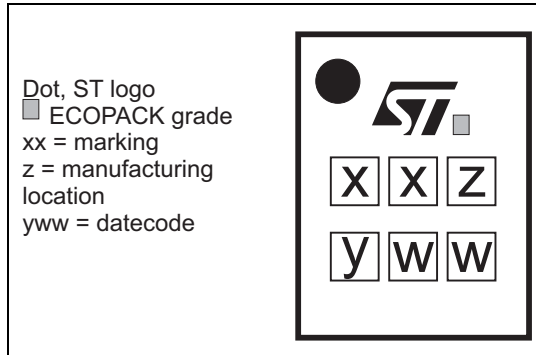


Figure 14. Recommended land pattern

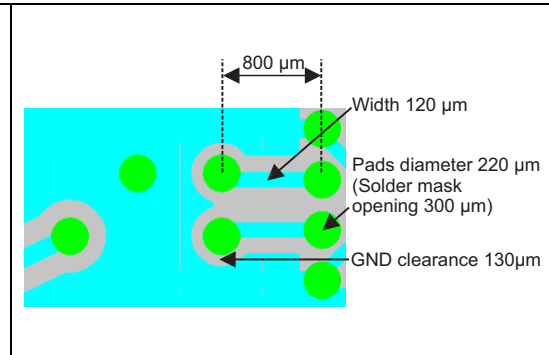
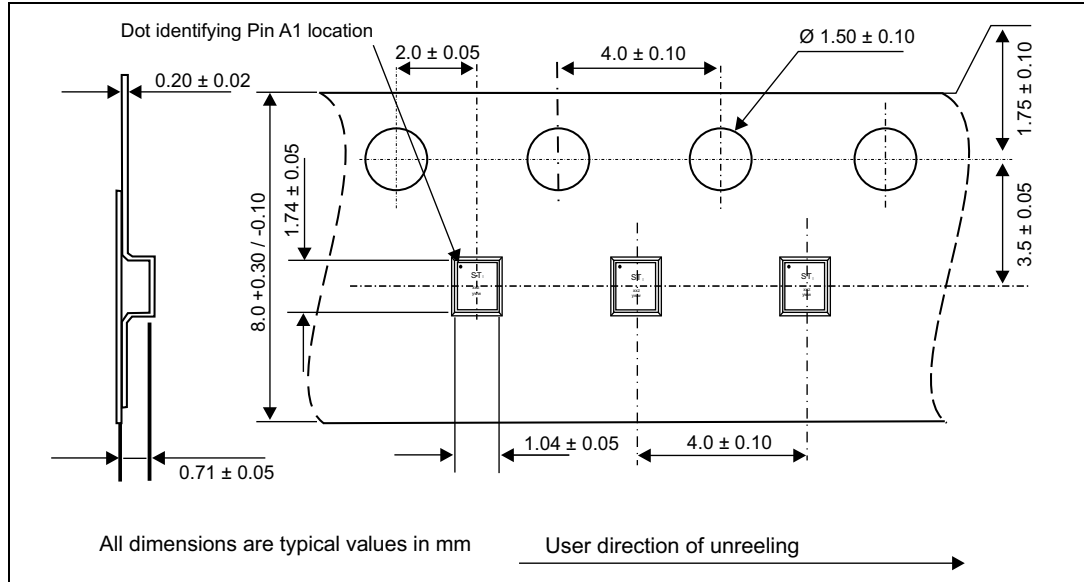


Figure 15. Flip Chip tape and reel specifications



Note: More information is available in the STMicroelectronics application notes: AN2348 Flip-Chip: "Package description and recommendations for use"

3 Ordering information

Table 4. Ordering information

Order code	Marking	Weight	Base Qty	Delivery mode
BALF-2690-02D3	SP	1.81 mg	5000	Tape and Reel

4 Revision history

Table 5. Document revision history

Date	Revision	Changes
27-Sep-2013	1	Initial release
19-Dec-2013	2	Added product weight in Table 4 and updated Table 1 .
19-Nov-2014	3	Added tape and reel dimensions.

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